L Number	Hits	Search Text	DB	Time stamp
1	23373	269/\$.ccls.	USPAT	2003/08/25 00:33
2	1015		USPAT	2003/08/25 00:33
2				
3	291		USPAT	2003/08/25 00:19
4	136	((269/\$.ccls. and (station or stations)) and recess) and arm	USPAT	2003/08/25 00:46
5	104	(269/\$.ccls. and (station or stations)) and ((station or stations)	USPAT	2003/08/25 00:22
J	104	with (wheel or wheels or disc or discs or circle or circles or	001711	2000/00/20 00:22
		round or circular or spin))		
6	15	269/\$.ccls. and (flexible adj arm)	USPAT	2003/08/25 00:45
7	4	269/\$.ccls. and (fluoropolymer)	USPAT	2003/08/25 00:46
8	181	269/\$.ccls. and teflon	USPAT	2003/08/25 00:46
9	3	(((269/\$.ccls. and (station or stations)) and recess) and arm)	USPAT	2003/08/25 00 ⁻ 55
		and teflon		
12	1	("3647043").PN.	USPAT	2003/08/25 00 56
14	23	269/\$ ccls and ((retaining adj arm) or (retain adj arm) or	USPAT	2003/08/25 00 59
14	23		USPAT	2003/08/23 00:59
-		(retainer adj arm))		
15	2308	((retaining adj arm) or (retain adj arm) or (retainer adj arm))	USPAT	2003/08/25 00 59
16	24	(((retaining adj arm) or (retain adj arm) or (retainer adj arm)))	USPAT	2003/08/25 00 59
, ,		and (wafer)		
1	0.5		LICDAT	2002/00/22 40 22
- j	65	((((article and (station or stations)) and ((MEMS adj die) or	USPAT	2003/08/22 18 33
į		(MEMS) or (die))) and apparatus) and (tool or arm)) and		
		(teflon)		
	13	MEMS adj die	USPAT	2002/11/26 23 34
-				
- 1	288	438/\$ ccls and MEMS	USPAT	2002/11/26 23 35
- ;	351	438/\$ ccls and (MEMS or (microelectromechanical))	USPAT	2002/11/27 00 54
-	94	29/603.17 or 29/603.19	USPAT	2002/11/26 23 53
	59	29/603.17.ccls. or 29/603.19.ccls.	USPAT	2002/11/26 23 53
Ī				2002/11/26 23 55
-	39	29/650.ccls.	USPAT	
-	824	269/55.ccls. or 269/56.ccls. or 269/57.ccls.	USPAT	2002/11/27 00 25
-	3	269/\$ ccls. and mems	USPAT	2002/11/27 00 25
_	3	269/\$ ccls. and (micromechanical)	USPAT	2002/11/27 00 26
	562	269/\$ ccls and semiconductor	USPAT	2002/11/27 00:44
-				
- !	131	257/\$ ccls_and MEMS	USPAT	2002/11/27 00:58
- *	705	438/455.ccls. or 438/456.ccls. or 438/458.ccls.	USPAT	2002/11/27 01:08
<u>-</u>	27	(438/455.ccls. or 438/456.ccls. or 438/458.ccls.) and teflon	USPAT	2002/11/27 01:09
	1	(414/935.ccls. or 414/936.ccls. or 414/937.ccls. or	USPAT	2003/05/08 13:17
-	'	,	00171	2003/00/00 13:11
		414/938 ccls. or 414/939.ccls. or 414/940.ccls. or		
		414/941 ccls.) and MEMS		
-	1561	414/935 ccls. or 414/936.ccls. or 414/937.ccls. or	USPAT	2003/05/08 13:25
1		414/938 ccls. or 414/939.ccls. or 414/940.ccls. or		
		414/941.ccls.		
1	•		LICDAT	2002/05/08 12:22
-		269/\$ ccls and (MEMS adj die)	USPAT	2003/05/08 13:23
-	578	269/\$.ccls and (semiconductor)	USPAT	2003/05/08 13:21
- 8	0	269/\$ ccls and (micro adj electro adj mechanical adj die)	USPAT	2003/05/08 13:21
_	1	269/\$ ccls and (micro adj electro adj mechanical)	USPAT	2003/05/08 13:23
			USPAT	2003/05/08 13:23
- 8	U	(414/935.ccls. or 414/936.ccls. or 414/937.ccls. or	USFAI	2003/03/00 13.23
		414/938 ccls. or 414/939 ccls. or 414/940 ccls. or		
		414/941 ccls.) and (MEMS adj die)		
_	1		USPAT	2003/05/08 13:23
	1	414/938 ccls. or 414/939.ccls. or 414/940.ccls. or		
		414/941 ccls.) and (MEMS)		
-	0	(414/935.ccls. or 414/936.ccls. or 414/937.ccls. or	USPAT	2003/05/08 13:23
		414/938 ccls. or 414/939.ccls. or 414/940.ccls. or		
		414/941 ccls.) and (micro adj electro adj mechanical)		
	_		LICOAT	2002/05/09 42:22
-	0	(414/935.ccls. or 414/936.ccls. or 414/937.ccls. or	USPAT	2003/05/08 13:23
		414/938 ccls. or 414/939.ccls. or 414/940.ccls. or		!
		414/941 ccls.) and (microelectromechanical-systems)		
_	258	(414/935.ccls. or 414/936.ccls. or 414/937.ccls. or	USPAT	2003/05/08 13:26
	200	414/938 ccls or 414/939.ccls or 414/940 ccls or	33.711	2000.20.00 .0.20
		orania. Schala		
		269/55 ccis	Jark.	2.003.00.22 ic is
	0	station and recess and (flexible adj reatining adj arm)	USPAT	2003/08/22 18 17
	_			
-	0	flexible adj reatining adj arm	USPAT	2003/08/22 18:17
-	27	flexible adj retaining adj arm	USPAT	2003/08/22 18:31